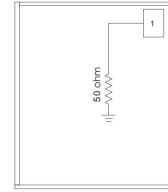


### Performance

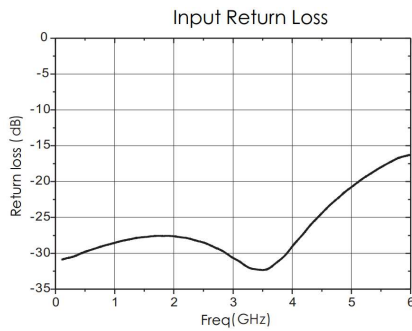
- Frequency: DC-5GHz
- Input Return Loss: -20dB
- Power Handling: 50W/CW
- Chip size: 3350\*2400\*300μm

### Function Diagram



Parameter	Min	Typical	Max	Unit
Frequency Range	DC-5			GHz
Input Return Loss	-	20	-	dB
Power Handling	-	-	50	W

### Test Curves (Die chip testing)



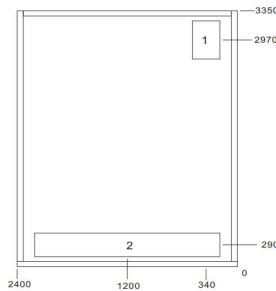
### Absolute Max Ratings

Max Handling Power	50W
Junction Temperature	175°C
Storage Temperature	-65~+150°C
Operating Temperature	-55~+125°C
Static Protection Grade	Class 1A



ELECTROSTATIC SENSITIVE DEVICE  
OBSERVE HANDLING PRECAUTIONS

### Outline Size

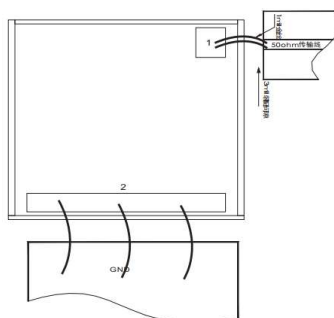


### Note:

Unit: um

1. Bottom side is gold plated
2. Bottom side is GND
3. Bonding pads is gold plated  
1): 300\*500μm, 2): 2000\*300μm
4. Don't bonding on thru holes
5. Tolerance: ±50um

### Assembly Drawing



### Bonding Pads Definition

Number	Symbol	Description
1	RFin	RF input port 50 ohm impedance
2	GND pad	Connect to GND by bonding wire
	GND	Bottom side of chip must be grounded

Typical assemble gap: 0.076~0.152mm (3~6mils)